Ragile 51.2Tbps Liquid Cooling Co-Packaged Ethernet Switch (Mechanical Demo)

Thanks to OIF's vibrant ecosystem, we have the honor to cooperate with Applied Optoelectronics Inc., Broadcom Inc., Intel Corporation, O-net Communications Ltd., Senko Advanced Components, Sumitomo Electric Industries Ltd., and TE Connectivity on this demonstration. Powered by these fellow members, this switch is presented to you with next-level capabilities:

1. **Extremely high "performance & density":**
   - Outline: 442 × 43.6 × 730mm
   - Broadcom 51.2Tbps Switch ASIC
   - Support up to 64 × 800GbE or 128 × 400GbE ports in 1RU box with Senko SN-MT optic interface

2. **Top-class Co-Packaged Optical module**
   - Equipped with Intel 3.2Tbps 8×400Gbps FR4 & DR4 3.2T optical module
   - Support both integrated-laser-source type and external-laser-input type optical modules
   - Optical modules are assembled on TE CPO sockets

3. **Modular Co-Packaged assembly**
   - 16x 3.2T optical modules are assembled with switch ASIC on a small size PCB
   - Decoupled with other parts and can be upgraded to 224Gbps SERDES easily

4. **Next generation external laser source – ELSFP**
   - ELSFP module with higher power and safer laser application from AOI and O-Net
   - Blind-mate electric and optic connector from TE and Sumitomo
   - Blind-mate ELS connection makes more data interface at front panel

5. **Cooled with cold-plate liquid cooling system**
   - High efficiency and quietness for switch ASIC and optical modules cooling
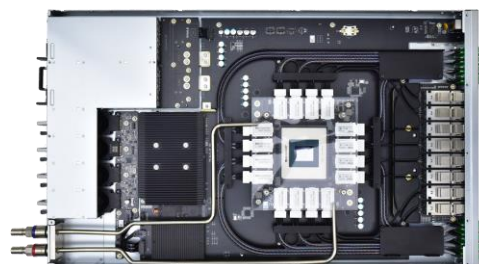
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